



# SN74AHCT16245 16-Bit Bus Transceivers With 3-State Outputs

## 1 Features

- Members of Texas Instruments' Widebus™ Family
- Inputs are TTL-Voltage Compatible
- Distributed  $V_{CC}$  and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17

## 2 Applications

- Telecom and Wireless Infrastructures
- Electronic Points of Sale
- Printers and Other Peripherals
- Motor Drives
- Health and Fitness

## 4 Simplified Schematic

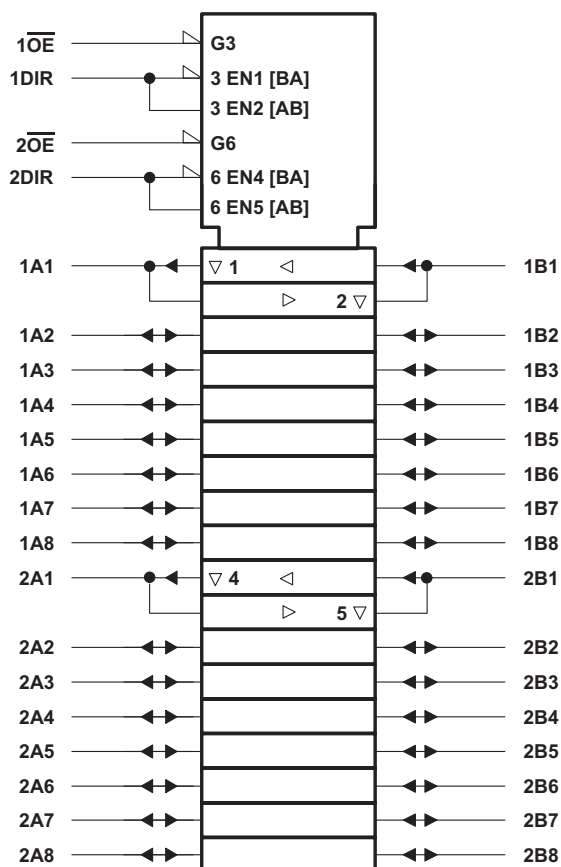
## 3 Description

The SN74AHCT16245 device is a 16-bit (dual-octal) noninverting 3-state transceiver designed for synchronous two-way communication between data buses.

**Device Information<sup>(1)</sup>**

| PART NUMBER   | PACKAGE    | BODY SIZE (NOM)    |
|---------------|------------|--------------------|
| SN74AHCT16245 | TVSOP (48) | 9.70 mm × 4.40 mm  |
|               | SSOP (48)  | 15.80 mm × 7.50 mm |
|               | TSSOP (48) | 12.50 mm × 6.10 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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## 5 Revision History

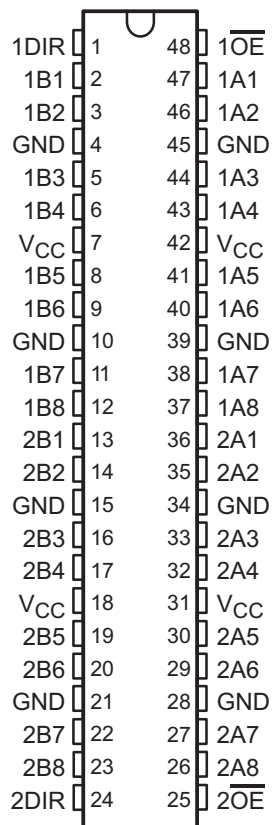
### Changes from Revision J (October 2000) to Revision K

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| • Updated document to new TI data sheet format. ....  | 1  |
| • Deleted Ordering Information table. ....  | 1  |
| • Deleted SN54AHCT16245 device from data sheet. ....  | 1  |
| • Added Applications. ....  | 1  |
| • Added Pin Functions table. ....   | 3  |
| • Added Handling Ratings table. ....  | 5  |
| • Changed MAX operating temperature to 125°C in Recommended Operating Conditions table. ....                | 5  |
| • Added Thermal Information table. ....   | 6  |
| • Added –40°C to 125°C range for SN74AHCT16245 in Electrical Characteristics table. ....                    | 6  |
| • Added $T_A = -40^{\circ}\text{C}$ to 125°C for SN74AHCT16245 in the Switching Characteristics table. .... | 7  |
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| • Added Power Supply Recommendations and Layout sections. ....  | 12 |

## 6 Pin Configuration and Functions

**SN74AHCT16245 . . . DGG, DGV, OR DL PACKAGE  
(TOP VIEW)**



**Pin Functions**

| PIN |                 | I/O | DESCRIPTION         |
|-----|-----------------|-----|---------------------|
| NO. | NAME            |     |                     |
| 1   | 1DIR            | I   | Direction pin 1     |
| 2   | 1B1             | I/O | 1B1 input or output |
| 3   | 1B2             | I/O | 1B2 input or output |
| 4   | GND             | —   | Ground pin          |
| 5   | 1B3             | I/O | 1B3 input or output |
| 6   | 1B4             | I/O | 1B4 input or output |
| 7   | V <sub>CC</sub> | —   | Power pin           |
| 8   | 1B5             | I/O | 1B5 input or output |
| 9   | 1B6             | I/O | 1B6 input or output |
| 10  | GND             | —   | Ground pin          |
| 11  | 1B7             | I/O | 1B7 input or output |
| 12  | 1B8             | I/O | 1B8 input or output |
| 13  | 2B1             | I/O | 2B1 input or output |
| 14  | 2B2             | I/O | 2B2 input or output |
| 15  | GND             | —   | Ground pin          |
| 16  | 2B3             | I/O | 2B3 input or output |
| 17  | 2B4             | I/O | 2B4 input or output |
| 18  | V <sub>CC</sub> | —   | Power pin           |

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**Pin Functions (continued)**

| PIN |                          | I/O | DESCRIPTION         |
|-----|--------------------------|-----|---------------------|
| NO. | NAME                     |     |                     |
| 19  | 2B5                      | I/O | 2B5 input or output |
| 20  | 2B6                      | I/O | 2B6 input or output |
| 21  | GND                      | —   | Ground pin          |
| 22  | 2B7                      | I/O | 2B7 input or output |
| 23  | 2B8                      | I/O | 2B8 input or output |
| 24  | 2DIR                     | —   | Direction pin 2     |
| 25  | 2 $\overline{\text{OE}}$ | I   | Output Enable 2     |
| 26  | 2A8                      | I/O | 2A8 input or output |
| 27  | 2A7                      | I/O | 2A7 input or output |
| 28  | GND                      | —   | Ground pin          |
| 29  | 2A6                      | I/O | 2A6 input or output |
| 30  | 2A5                      | I/O | 2A5 input or output |
| 31  | V <sub>CC</sub>          | —   | Power pin           |
| 32  | 2A4                      | I/O | 2A4 input or output |
| 33  | 2A3                      | I/O | 2A3 input or output |
| 34  | GND                      | —   | Ground pin          |
| 35  | 2A2                      | I/O | 2A2 input or output |
| 36  | 2A1                      | I/O | 2A1 input or output |
| 37  | 1A8                      | I/O | 1A8 input or output |
| 38  | 1A7                      | I/O | 1A7 input or output |
| 39  | GND                      | —   | Ground pin          |
| 40  | 1A6                      | I/O | 1A6 input or output |
| 41  | 1A5                      | I/O | 1A5 input or output |
| 42  | V <sub>CC</sub>          | —   | Power pin           |
| 43  | 1A4                      | I/O | 1A4 input or output |
| 44  | 1A3                      | I/O | 1A3 input or output |
| 45  | GND                      | —   | Ground pin          |
| 46  | 1A2                      | I/O | 1A2 input or output |
| 47  | 1A1                      | I/O | 1A1 input or output |
| 48  | 1 $\overline{\text{OE}}$ | I   | Output Enable 1     |

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|   |                           |                                     |  | MIN  | MAX                   | UNIT |
|---|---------------------------|-------------------------------------|--|------|-----------------------|------|
| V <sub>CC</sub>                                   |                           | Supply voltage range                |  | −0.5 | 7                     | V    |
| V <sub>I</sub>                                    | Control Inputs            | Input voltage range <sup>(2)</sup>  |  | −0.5 | 7                     | V    |
| V <sub>O</sub>                                    | I/O                       | Output voltage range <sup>(2)</sup> |  | −0.5 | V <sub>CC</sub> + 0.5 | V    |
| I <sub>IK</sub>                                   | Control Inputs            | Input clamp current                 | V <sub>I</sub> < 0                                     |      | −20                   | mA   |
| I <sub>OK</sub>                                   | I/O                       | Output clamp current                | V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> |      | ±20                   | mA   |
| I <sub>O</sub>                                    | Continuous output current |                                     | V <sub>O</sub> = 0 to V <sub>CC</sub>                  |      | ±25                   | mA   |
| Continuous current through V <sub>CC</sub> or GND |                           |                                     |  |      | ±75                   | mA   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 7.2 Handling Ratings

|             |                           |  |  | MIN | MAX  | UNIT |
|-------------|---------------------------|--|--|-----|------|------|
| $T_{stg}$   | Storage temperature range |  |  | −65 | 150  | °C   |
| $V_{(ESD)}$ | Electrostatic discharge   | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>              |  | 0   | 1500 | V    |
|             |                           | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> |  | 0   | 2000 |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                     |                                    |  |  | SN74AHCT16245 |          | UNIT |
|---------------------|------------------------------------|--|--|---------------|----------|------|
|                     |                                    |  |  | MIN           | MAX      |      |
| $V_{CC}$            | Supply voltage                     |  |  | 4.5           | 5.5      | V    |
| $V_{IH}$            | High-level input voltage           |  |  | 2             |          | V    |
| $V_{IL}$            | Low-level input voltage            |  |  |               | 0.8      | V    |
| $V_I$               | Input voltage                      |  |  | 0             | 5.5      | V    |
| $V_{IO}$            | Input/Output voltage, A or B pins  |  |  | 0             | $V_{CC}$ | V    |
| $I_{OH}$            | High-level output current          |  |  |               | −8       | mA   |
| $I_{OL}$            | Low-level output current           |  |  |               | 8        | mA   |
| $\Delta t/\Delta v$ | Input transition rise or fall rate |  |  |               | 20       | ns/V |
| $T_A$               | Operating free-air temperature     |  |  | −40           | 125      | °C   |

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI Application Report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

## 7.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |  | SN74AHCT16245 |      |      | UNIT |
|-------------------------------|--|---------------|------|------|------|
|                               |  | DGG           | DGV  | DL   |      |
|                               |  | 48 PINS       |      |      |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 68.1          | 79.3 | 61.0 | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 22.6          | 31.3 | 30.8 |      |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 35.0          | 42.3 | 32.8 |      |
| Ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 1.3           | 2.4  | 8.4  |      |
| Ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 34.7          | 41.8 | 32.5 |      |
| R <sub>θJC(bot)</sub>         | Junction-to-case (bottom) thermal resistance | n/a           | n/a  | n/a  |      |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                       | TEST CONDITIONS  | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     |       | SN74AHCT16245 |      | –40°C to 125°C<br>SN74AHCT16245 |      | UNIT |
|---------------------------------|--|-----------------|-----------------------|-----|-------|---------------|------|---------------------------------|------|------|
|                                 |  |                 | MIN                   | TYP | MAX   | MIN           | MAX  | MIN                             | MAX  |      |
| V <sub>OH</sub>                 | I <sub>OH</sub> = –50 μA   | 4.5 V           | 4.4                   | 4.5 |       | 4.4           |      | 4.4                             |      | V    |
|                                 | I <sub>OH</sub> = –8 mA  |                 | 3.94                  |     |       | 3.8           |      | 3.8                             |      |      |
| V <sub>OL</sub>                 | I <sub>OL</sub> = 50 μA  | 4.5 V           |                       |     | 0.1   |               | 0.1  |                                 | 0.1  | V    |
|                                 | I <sub>OL</sub> = 8 mA   |                 |                       |     | 0.36  |               | 0.44 |                                 | 0.44 |      |
| I <sub>I</sub>                  | $\overline{\text{OE}}$ or DIR<br>V <sub>I</sub> = V <sub>CC</sub> or GND | 0 V to 5.5 V    |                       |     | ±0.1  |               | ±1   |                                 | ±1   | μA   |
| I <sub>OZ</sub> <sup>(1)</sup>  | A or B<br>Inputs<br>V <sub>O</sub> = V <sub>CC</sub> or GND              |                 |                       |     | ±0.25 |               | ±2.5 |                                 | ±2.5 | μA   |
| I <sub>CC</sub>                 | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0              | 5.5 V           |                       |     | 4     |               | 40   |                                 | 40   | μA   |
| ΔI <sub>CC</sub> <sup>(2)</sup> | One input at 3.4 V,<br>Other inputs at V <sub>CC</sub> or GND            | 5.5 V           |                       |     | 1.35  |               | 1.5  |                                 | 1.5  | mA   |
| C <sub>i</sub>                  | $\overline{\text{OE}}$ or DIR<br>V <sub>I</sub> = V <sub>CC</sub> or GND | 5 V             |                       | 2.5 | 10    |               | 10   |                                 | 10   | pF   |
| C <sub>io</sub>                 | A or B<br>Inputs   | 5 V             |                       | 4   |       |               |      |                                 |      | pF   |

(1) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

(2) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 7.6 Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 2)

| PARAMETER   | FROM<br>(INPUT) | TO<br>(OUTPUT) | LOAD<br>CAPACITANCE  | $T_A = 25^\circ\text{C}$ |                    | SN74AHCT16245 |      | $T_A = -40^\circ\text{C}$ to $125^\circ\text{C}$<br>SN74AHCT16245 |      | UNIT |
|-------------|-----------------|----------------|----------------------|--------------------------|--------------------|---------------|------|---|------|------|
|             |                 |                |                      | TYP                      | MAX                | MIN           | MAX  | MIN   | MAX  |      |
| $t_{PLH}$   | A or B          | B or A         | $C_L = 15\text{ pF}$ | 4.5 <sup>(1)</sup>       | 8.5 <sup>(1)</sup> | 1             | 9.5  | 1   | 11   | ns   |
| $t_{PHL}$   |                 |                |                      | 4.5 <sup>(1)</sup>       | 8.5 <sup>(1)</sup> | 1             | 9.5  | 1   | 11   |      |
| $t_{PZH}$   | $\overline{OE}$ | A or B         | $C_L = 15\text{ pF}$ | 8.9 <sup>(1)</sup>       | 13 <sup>(1)</sup>  | 1             | 14   | 1   | 15   | ns   |
| $t_{PZL}$   |                 |                |                      | 8.9 <sup>(1)</sup>       | 13 <sup>(1)</sup>  | 1             | 14   | 1   | 15   |      |
| $t_{PHZ}$   | $\overline{OE}$ | A or B         | $C_L = 15\text{ pF}$ | 9.2 <sup>(1)</sup>       | 14 <sup>(1)</sup>  | 1             | 15   | 1   | 15.7 | ns   |
| $t_{PLZ}$   |                 |                |                      | 9.2 <sup>(1)</sup>       | 14 <sup>(1)</sup>  | 1             | 15   | 1   | 15.7 |      |
| $t_{PLH}$   | A or B          | B or A         | $C_L = 50\text{ pF}$ | 7                        | 9.5                | 1             | 10.5 | 1   | 12   | ns   |
| $t_{PHL}$   |                 |                |                      | 5.3                      | 9.5                | 1             | 10.5 | 1   | 12   |      |
| $t_{PZH}$   | $\overline{OE}$ | A or B         | $C_L = 50\text{ pF}$ | 8.3                      | 14                 | 1             | 15   | 1   | 16   | ns   |
| $t_{PZL}$   |                 |                |                      | 8.3                      | 14                 | 1             | 15   | 1   | 16   |      |
| $t_{PHZ}$   | $\overline{OE}$ | A or B         | $C_L = 50\text{ pF}$ | 8                        | 14                 | 1             | 15   | 1   | 15.7 | ns   |
| $t_{PLZ}$   |                 |                |                      | 8                        | 14                 | 1             | 15   | 1   | 15.7 |      |
| $t_{sk(o)}$ |                 |                | $C_L = 50\text{ pF}$ |                          | 1 <sup>(2)</sup>   |               | 1    |   | 1    | ns   |

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(2) On products compliant to MIL-PRF-38535, this parameter does not apply.

## 7.7 Noise Characteristics

$V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$ <sup>(1)</sup>

| PARAMETER   |  | SN74AHCT16245 |      |      | UNIT |
|-------------|--|---------------|------|------|------|
|             |  | MIN           | TYP  | MAX  |      |
| $V_{OL(P)}$ | Quiet output, maximum dynamic $V_{OL}$ |               | 0.6  | 0.8  | V    |
| $V_{OL(V)}$ | Quiet output, minimum dynamic $V_{OL}$ |               | −0.6 | −0.8 | V    |
| $V_{OH(V)}$ | Quiet output, minimum dynamic $V_{OH}$ |               | 4.8  |      | V    |
| $V_{IH(D)}$ | High-level dynamic input voltage       | 2             |      |      | V    |
| $V_{IL(D)}$ | Low-level dynamic input voltage        |               |      | 0.8  | V    |

(1) Characteristics are for surface-mount packages only.

## 7.8 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS  | TYP | UNIT |
|-----------|--|-----|------|
| $C_{pd}$  | Power dissipation capacitance<br>No load, $f = 1\text{ MHz}$ | 17  | pF   |

## 7.9 Typical Characteristics

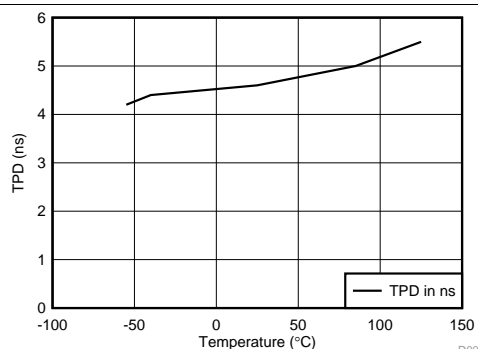
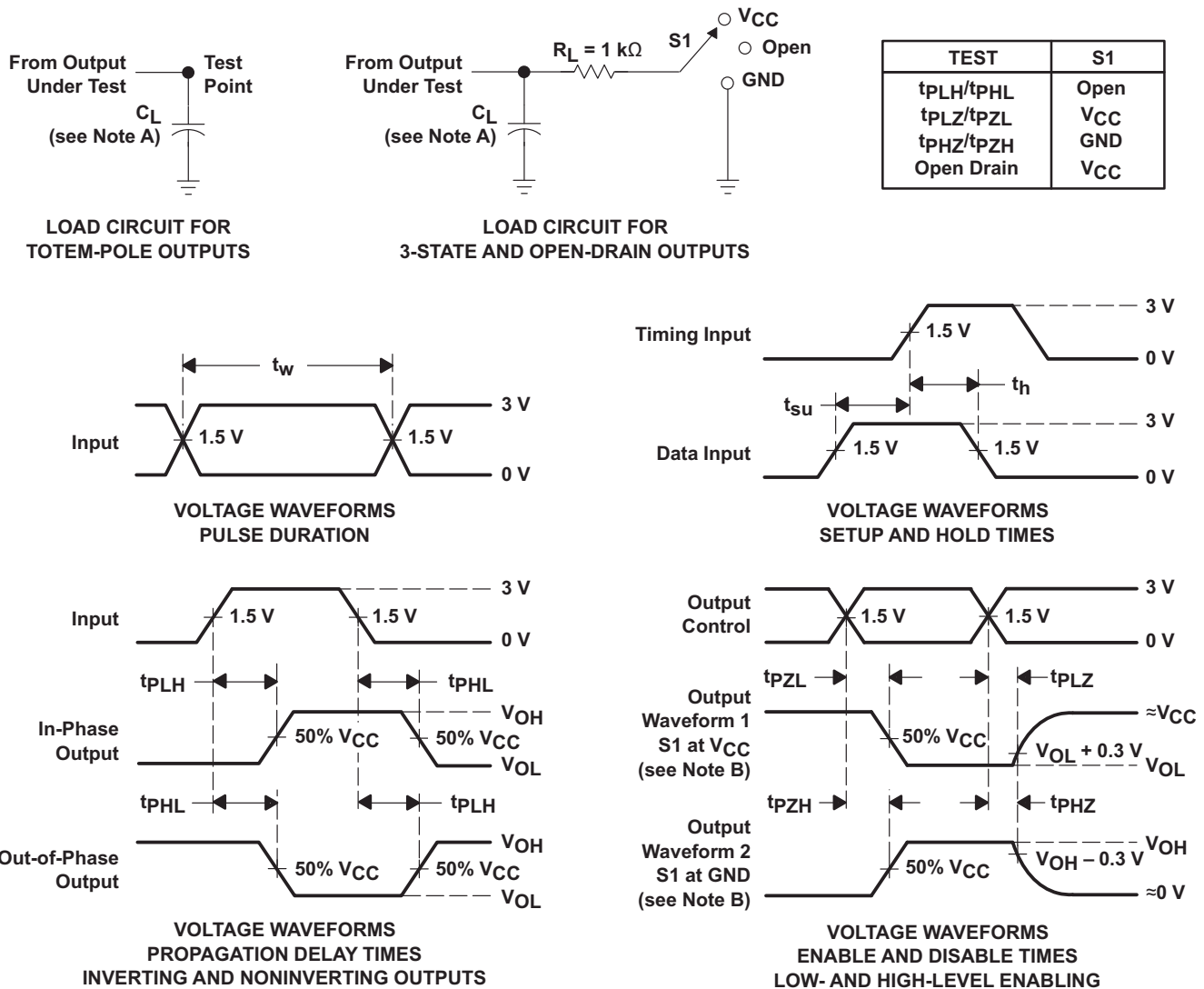


Figure 1. TPD vs Temperature

## 8 Parameter Measurement Information



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.

**Figure 2. Load Circuit and Voltage Waveforms**

## 9 Detailed Description

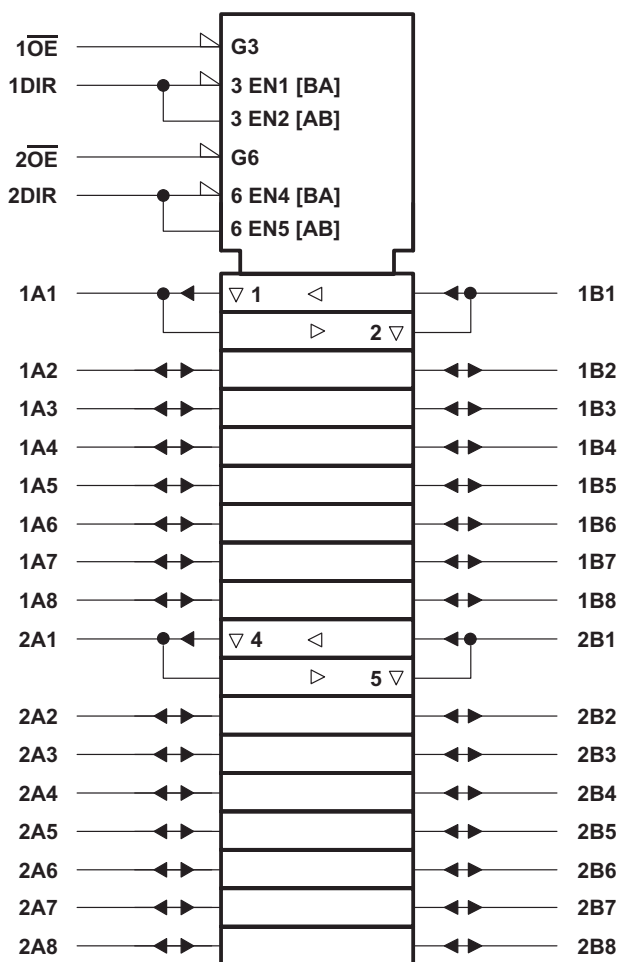
### 9.1 Overview

The SN74AHCT16245 device is a 16-bit (dual-octal) noninverting 3-state transceiver designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

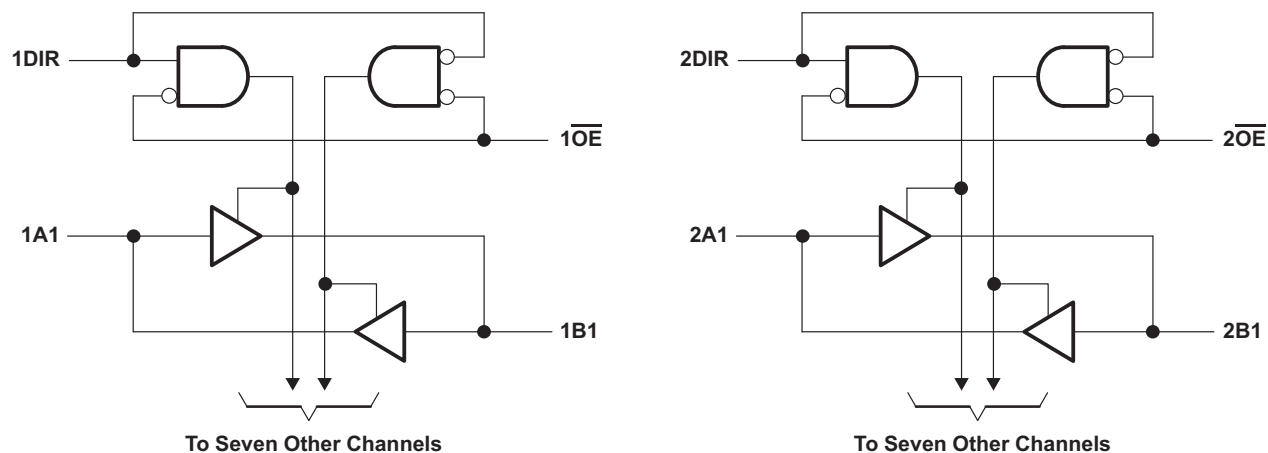
### 9.2 Functional Block Diagrams



A. † This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**Figure 3. Logic Symbol**

## Functional Block Diagrams (continued)



**Figure 4. Logic Diagram (Positive Logic)**

### 9.3 Feature Description

- TTL inputs
  - Lowered switching threshold allows up translation 3.3 V to 5 V
- Slow edges reduce output ringing

### 9.4 Device Functional Modes

**Table 1. Function Table  
(Each 8-bit Transceiver)**

| INPUTS          |     | OPERATION       |
|-----------------|-----|-----------------|
| $\overline{OE}$ | DIR |                 |
| L               | L   | B data to A bus |
| L               | H   | A data to B bus |
| H               | X   | Isolation       |

## 10 Application and Implementation

### 10.1 Application Information

The SN74AHCT16245 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of 0.8-V  $V_{IL}$  and 2-V  $V_{IH}$ . This feature makes the device ideal for translating up from 3.3 V to 5 V. Figure 6 shows this type of translation.

### 10.2 Typical Application

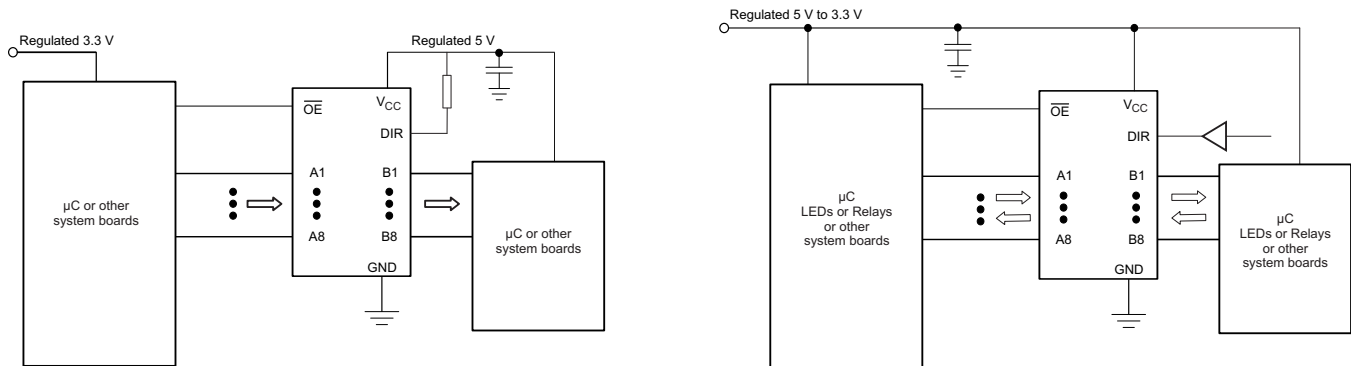


Figure 5. Typical Application Diagram

#### 10.2.1 Design Requirements

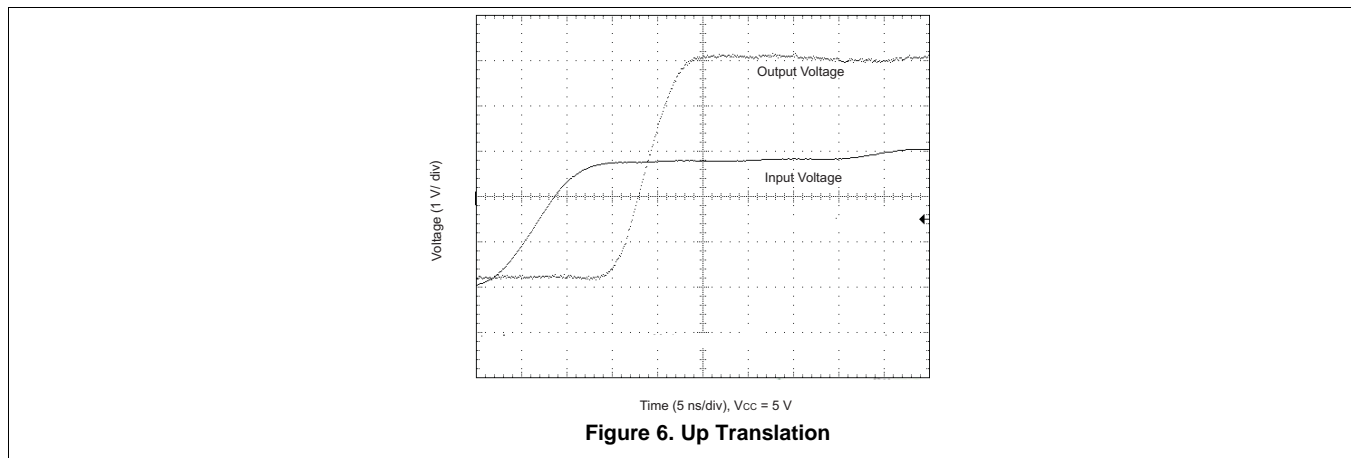
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions:
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [Recommended Operating Conditions](#) table.
  - For specified high and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions:
  - Load currents should not exceed 25 mA per output and 75 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

## Typical Application (continued)

### 10.2.3 Application Curves



## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended and if there are multiple  $V_{CC}$  pins than 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 7](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver.

### 12.2 Layout Example

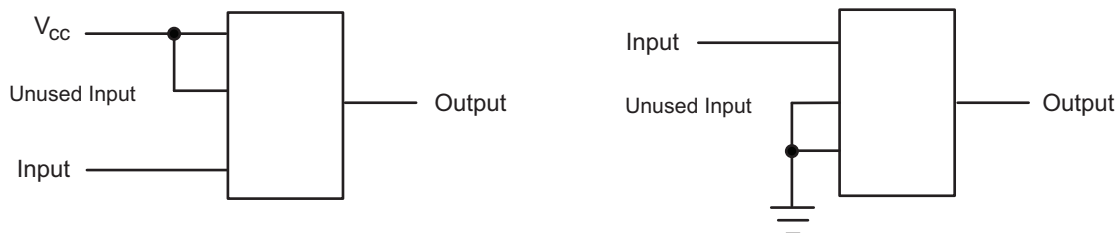


Figure 7. Layout Diagram

## 13 Device and Documentation Support

### 13.1 Trademarks

Widebus is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable part number             | Status<br>(1) | Material type<br>(2) | Package   Pins   | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|-----------------------------------|---------------|----------------------|------------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| 74AHCT16245DGGRG4                 | Active        | Production           | TSSOP (DGG)   48 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AHCT16245           |
| <a href="#">SN74AHCT16245DGGR</a> | Active        | Production           | TSSOP (DGG)   48 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AHCT16245           |
| <a href="#">SN74AHCT16245DGVR</a> | Active        | Production           | TVSOP (DGV)   48 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | HF245               |
| <a href="#">SN74AHCT16245DL</a>   | Obsolete      | Production           | SSOP (DL)   48   | -                     | -           | Call TI                              | Call TI                           | -40 to 125   | AHCT16245           |
| <a href="#">SN74AHCT16245DLR</a>  | Active        | Production           | SSOP (DL)   48   | 1000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AHCT16245           |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

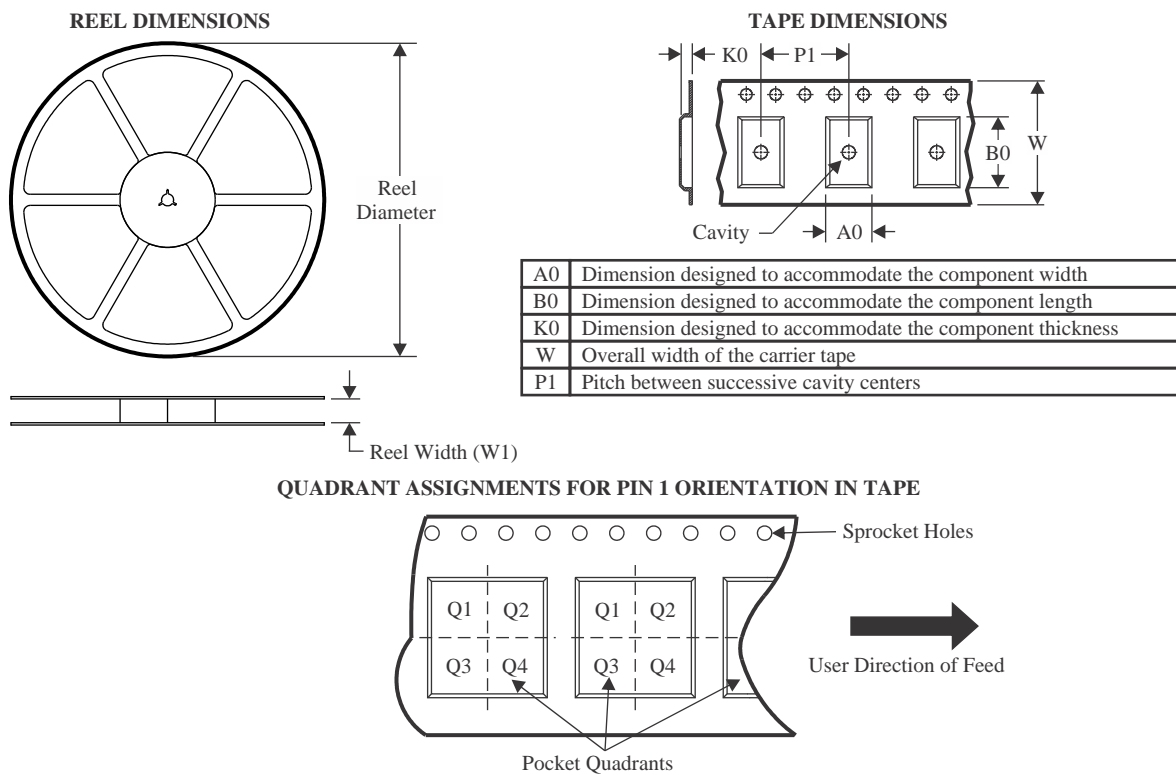
<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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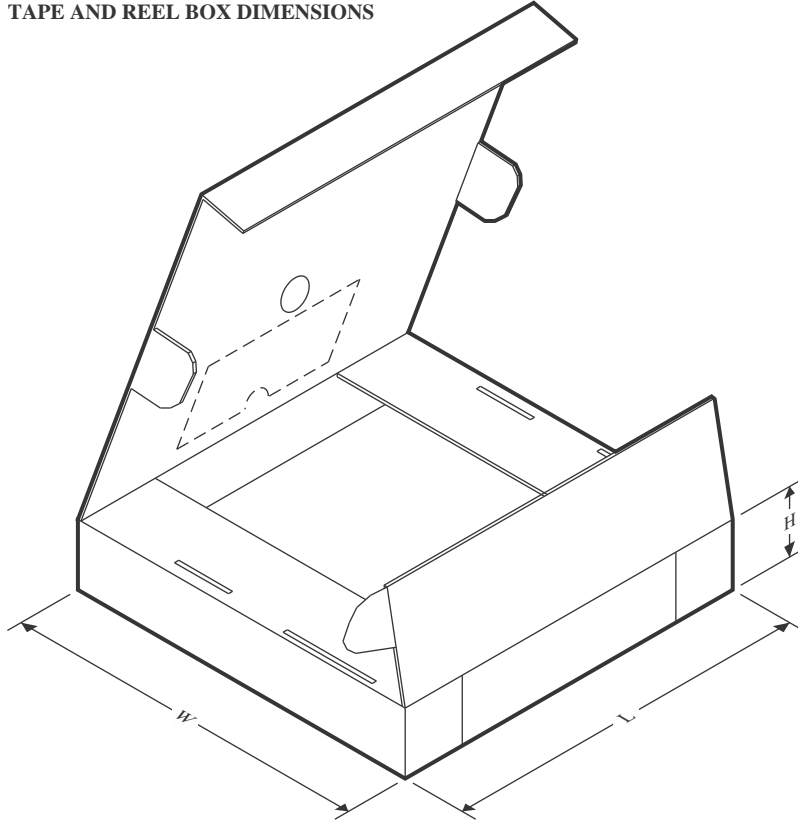
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device            | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AHCT16245DGGR | TSSOP        | DGG             | 48   | 2000 | 330.0              | 24.4               | 8.6     | 13.0    | 1.8     | 12.0    | 24.0   | Q1            |
| SN74AHCT16245DGVR | TVSOP        | DGV             | 48   | 2000 | 330.0              | 16.4               | 7.1     | 10.2    | 1.6     | 12.0    | 16.0   | Q1            |
| SN74AHCT16245DLR  | SSOP         | DL              | 48   | 1000 | 330.0              | 32.4               | 11.35   | 16.2    | 3.1     | 16.0    | 32.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS

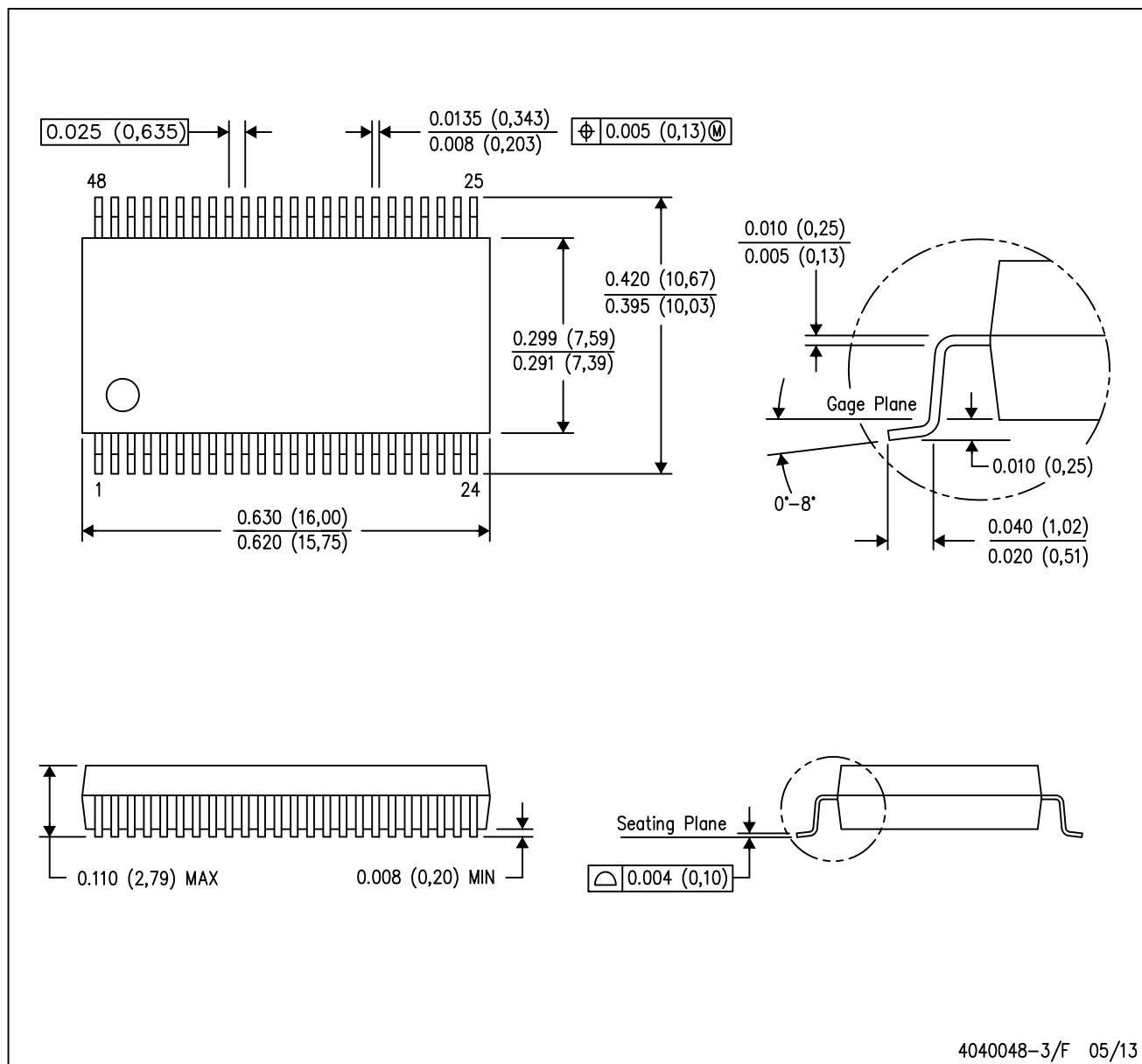


\*All dimensions are nominal

| Device            | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AHCT16245DGGR | TSSOP        | DGG             | 48   | 2000 | 367.0       | 367.0      | 45.0        |
| SN74AHCT16245DGVR | TVSOP        | DGV             | 48   | 2000 | 356.0       | 356.0      | 35.0        |
| SN74AHCT16245DLR  | SSOP         | DL              | 48   | 1000 | 367.0       | 367.0      | 55.0        |

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE

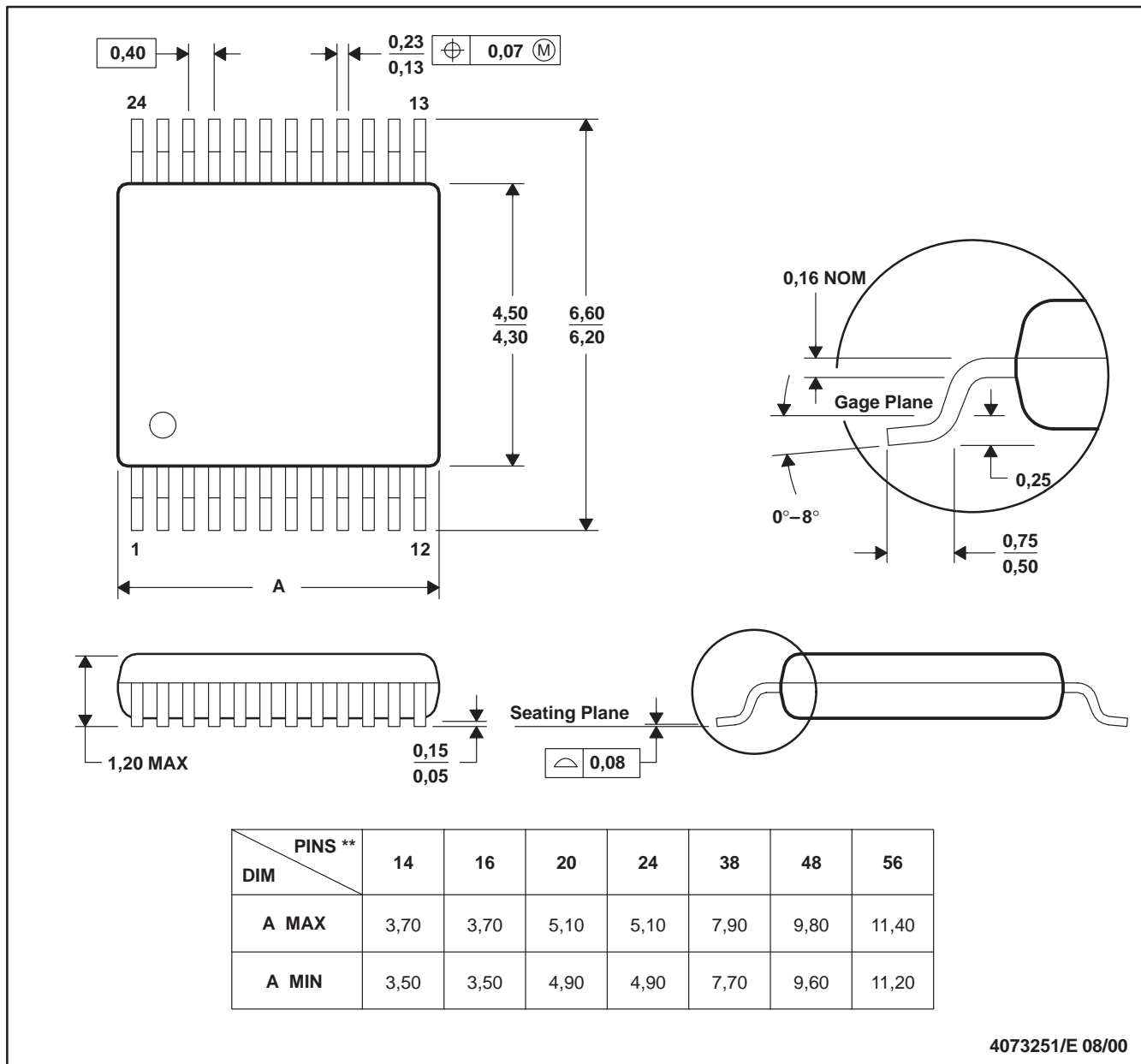


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MO-118

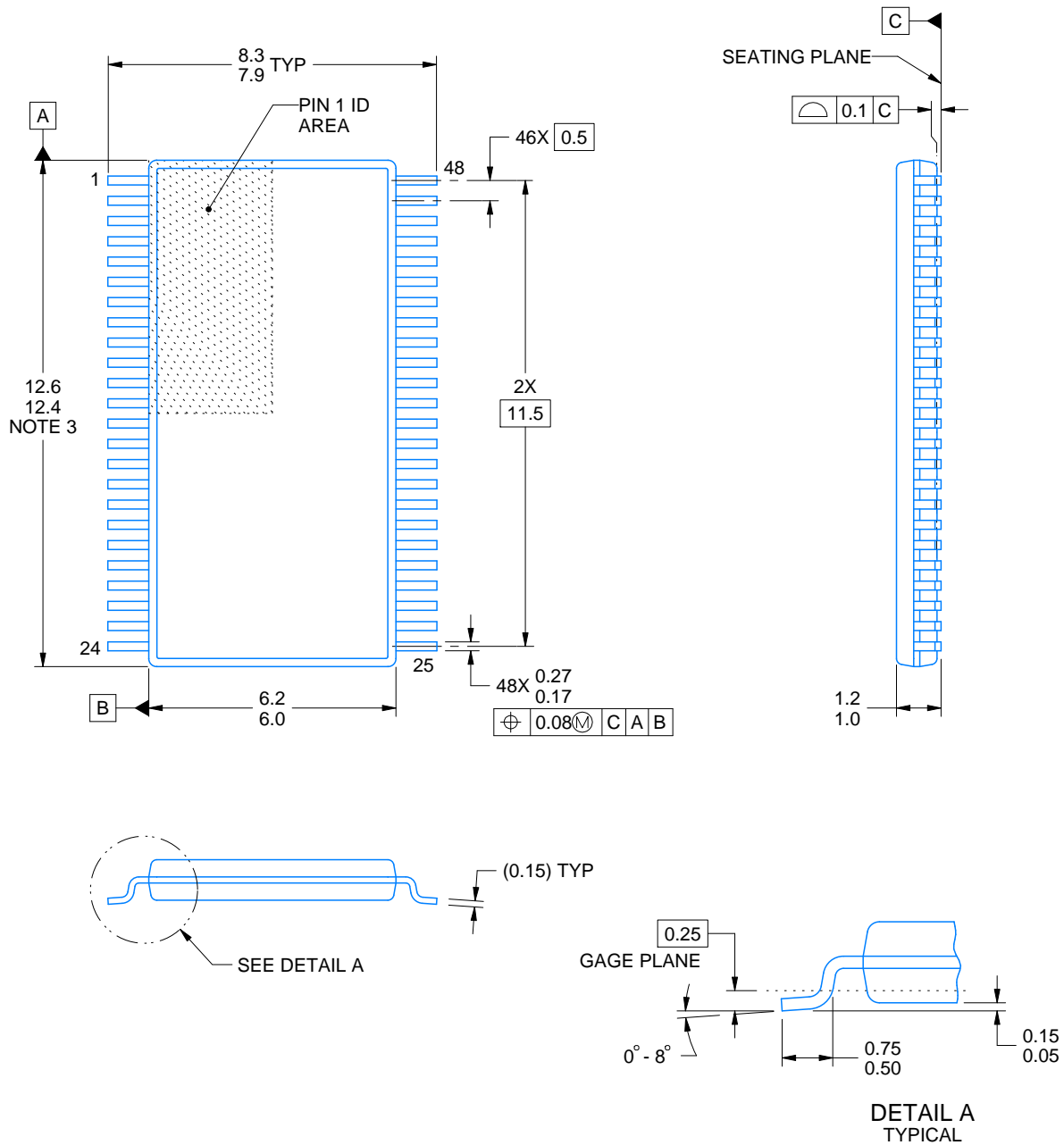
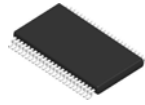
## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



4214859/B 11/2020

## NOTES:

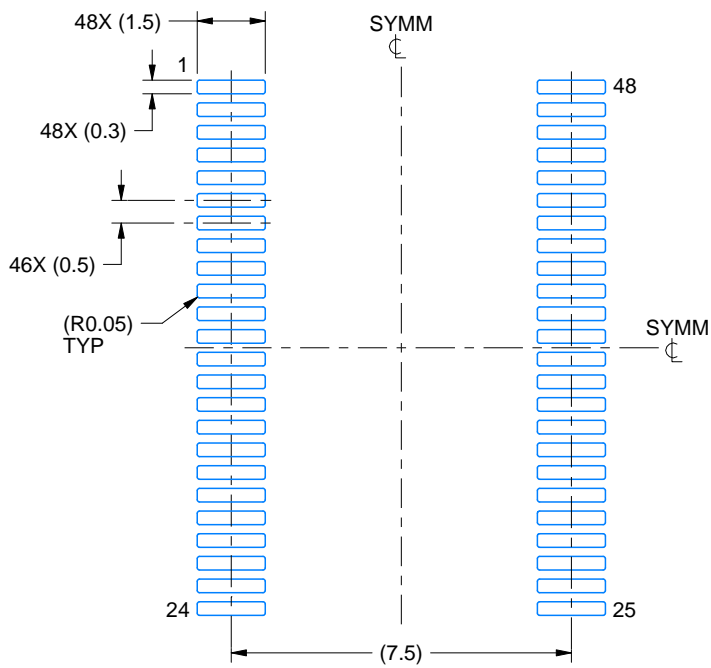
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

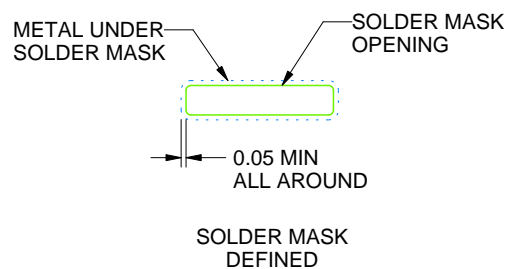
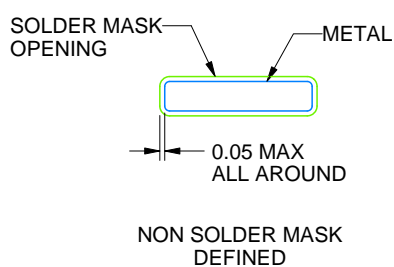
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

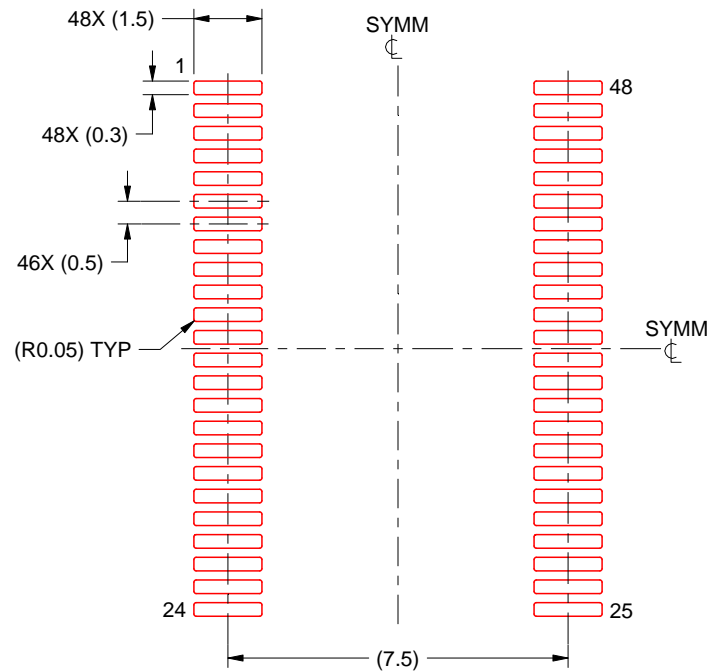
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

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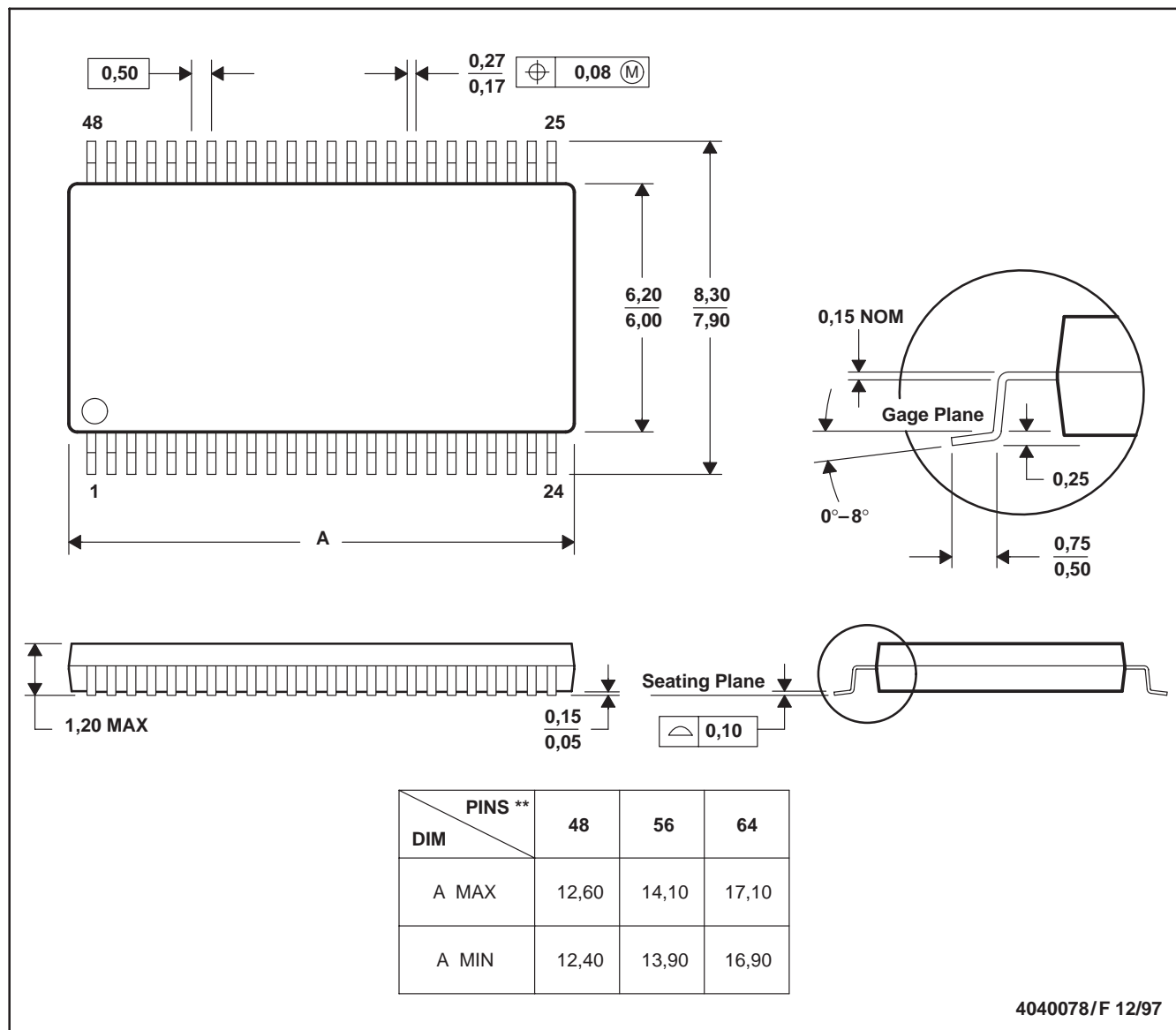
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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